

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**In re Application of:**

Kling, et al.	Conf. No.: 7890
Application No: 09/974,023	Art Unit: 2814
Filed: October 10, 2001	Examiner: Hoai Pham
For: <i>Embedded Capacitor Multi-Chip Modules</i>	Atty. Docket: RAK-001.02

CERTIFICATE OF FIRST CLASS MAILING

I hereby certify that the foregoing documents are being deposited with the United States Postal Service as First Class Mail, postage prepaid, in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313, on this 25th day of July, 2003.


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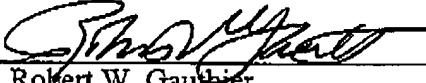
Attn: Official Draftsperson

Sir:

Applicant hereby submits three (4) sheets of formal drawings containing Figs. 1-7 for the above-referenced application.

Should there be any questions after reviewing this paper, the Examiner is invited to contact the undersigned at 617-832-1175.

Respectfully Submitted,


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